

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): Wafer comprising a thermostable α -amylase present in an amount of 10 to 1000 units per gram of a final dough batter, an in-situ modified starch, and a humidity that is not greater than 6%.

Claim 2 (canceled):

Claim 3 (previously presented): Wafer according to claim 1 wherein the wafer is selected from the group consisting of a flat wafer, a sugar wafer, and a three dimension shaped wafer.

Claim 4 (canceled):

Claim 5 (previously presented): Wafer according to claim 1 also comprising at least one of a proteinases and xylanases.

Claim 6 (previously presented): Wafer according to claim 1 comprising at least one component selected from the group consisting of gassing agents and gas generating microorganisms.

Claim 7 (previously presented): Wafer according to claim 1 wherein the molecular weight of starch has been reduced.

Claim 8 (previously presented): Wafer according to claim 1 wherein the α -amylase is of an origin selected from the group consisting of bacterial, fungal and plants origin.

Claim 9 (currently amended): Process for making a wafer comprising the steps of making a wafer batter or a dough by mixing at least flour, water and a thermostable α -amylase present in an amount of 10 to 1000 units per gram of a final dough batter and baking it on at least one hot surface, the wafer having a humidity at the end of the baking step that is not greater than 6%.

Claims 10-11 (canceled):

Claim 12 (previously presented): Process according to claim 9 wherein the wafer batter or dough further comprises at least one component selected from the group consisting of protease and xylanase.

Claim 13 (previously presented): Process according to claim 9 wherein the wafer batter or dough comprises at least one component selected from the group consisting of gassing agents and gas generating microorganisms.

Claim 14 (currently amended): A method of using thermostable α -amylase to manipulate textural attributes of a wafer comprising the steps of adding α -amylase to a wafer batter and baking the wafer batter, the wafer having a humidity at the end of the baking step that is not greater than 6%, wherein the thermostable α -amylase is present in an amount of 10 to 1000 units per gram of a final dough batter.

Claim 15 (previously presented): The method of claim 14, the wafer batter comprising at least a gassing agent.

Claim 16 (currently amended): Method for manufacturing a wafer comprising the steps of modifying a starch in a wafer batter without increasing batter viscosity by treating the batter with thermostable α -amylase, and baking the wafer batter, the wafer having a humidity at the end of the baking step that is not greater than 6%, wherein the thermostable α -amylase is present in an amount of 10 to 1000 units per gram of a final dough batter.

Claim 17 (previously presented): Method according to claim 16 wherein the wafer batter does not stick to baking plates.

Claims 18-19 (canceled):

Claim 20 (previously presented): Wafer according to claim 1 wherein soluble dextrins have been produced.